

L Number	Hits	Search Text	DB	Time stamp
1	2218	165/80.3,80.4.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/21 15:27
2	228	165/80.3,80.4.ccls. and pump	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/21 15:28

L Number	Hits	Search Text	DB	Time stamp
1	3510	integrated adj circuit adj die	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/21 07:21
3	42	((integrated adj circuit adj die) and (solder adj bumps)) and (active adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/21 07:25
4	0	((integrated adj circuit adj die) and (solder adj bumps)) and (active adj surface)) and (cooling adj fluid)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/21 07:29
5	0	((integrated adj circuit adj die) and (solder adj bumps)) and (active adj surface)) and (air adj filled adj chamber)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/21 07:27
6	0	(integrated adj circuit adj die) and (air adj filled adj chamber)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/21 07:28
8	5	((integrated adj circuit adj die) and (cooling adj fluid)) and (solder adj bumps)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/21 07:29
7	36	(integrated adj circuit adj die) and (cooling adj fluid)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/21 07:34
2	296	(integrated adj circuit adj die) and (solder adj bumps)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/21 07:58
9	927	361/699	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/21 08:14
10	116	(integrated adj circuit adj die) and (heat adj spreader)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/21 08:42
11	2883	165/80.3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/21 08:43
12	192	165/80.3 and (integrated adj circuit adj package)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/21 08:49
13	747	165/80.3 and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/21 08:50
14	77	(165/80.3 and substrate) and (cooling adj fluid)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/21 08:57
15	57	165/80.3 and (solder adj bumps)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/21 09:00